



Process Change Notification

PCN Number: PCN-000015

PCN Notification Date: March 7th, 2024

Initial PCN

Lead Frame Supplier 2nd Source for 16L SOIC component material

Dear Customer,

This Initial PCN notification is to advise you of the following change(s):

- Due to on-going supply constraints and overall demand our supply base (ASE-CL) is adding a 2nd Source Lead Frame Supplier (Mitsui High-Tec, Inc.) for the 16L SOIC component material to ensure continuity of supply.
- There is no anticipated adverse impact to the Fit, Form, Function, Quality and/or Reliability of said product as all processes and material remain the same.

Note: The 2nd Source Supplier (Mitsui High-Tec, Inc.) has been a well-established / qualified lead frame material supplier of ASE-CL for several years.

A Final PCN is forthcoming and will depict the results of the package level qualification.

Upon successful completion of the package level qualification, the change will be effective immediately. Thereafter, utilization of the 2nd source supplier lead frame material will commence, be a running change through Q2_2024 and fully transition in 2024.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

Quality Systems Administrator
Cirrus Logic Corporate Quality
Phone: +1(512) 851-4000



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Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

Title:		Lead Frame Supplier 2nd Source for 16L SOIC component material					
Customer Contact:		Local Field Sales Representative		Phone:	(512) 851-4000	Dept:	Corporate Quality
Proposed 1 st Ship Date:			Q2 2024	Estimated Sample Availability Date:			Upon Request
Change Type:							
	Assembly Site		Assembly Process		X	Assembly Materials	
	Wafer Fab Site		Wafer Fab Process			Wafer Fab Materials	
	Wafer Bump Site		Wafer Bump Process			Wafer Bump Material	
	Test Site		Test Process			Design	
	Electrical Specification		Mechanical Specification			Part Number	
	Packing/Shipping/Labeling	X	Other				
Comments:		Addition of 2 nd Source Lead Frame Supplier (Mitsui High-Tec, Inc.)					

PCN Details

Description of Change:

Addition of 2nd Source Lead Frame Supplier (Mitsui High-Tec, Inc.) to support 16L SOIC component material.
Note: All processes and material remain the same.

Reason for Change:

To maintain continuity of material supply.

Anticipated Impact on Form, Fit, Function, Quality or Reliability:

There is no anticipated adverse impact to the Fit, Form, Function, Quality and/or Reliability of said product as all processes and material remain the same.

Anticipated Impact on Material Declaration:

☒ No Impact to the Material Declaration ☐ Material Declarations or Product Content reports are driven from production data and will be available following the production release.

Product Affected:

Device	Cirrus Logic Part Number
1	CS5490-ISZ
2	CS5490-ISZR

Changes To Product Identification Resulting From This PCN:

No change to product identification

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The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

CS5490-ISZ - Qualification

CS5490-ISZ Qualification: ☒ Plan ☐ Test Results			
Reliability Test	Standard	Conditions	Sample Size (PASS/FAIL)
WBP (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) (3 Lots – 5 units / Lot)	(Results Are Pending)
WBS (Wire Bond Shear)	JESD22 B116	Paragraph 4 (Procedure) (3 Lots – 5 units / Lot)	(Results Are Pending)
SD (Solderability)	JESD22 B102	245°C / 8 hr steam age before SD (3 Lot – 5 units)	(Results Are Pending)
PD (Physical Dimensions)	JESD22 B100 + B108	Package outline per JESD95 Cpk > 1.50 per JESD95 (30 - Units)	(Results Are Pending)
Pre-Conditioning	JEDEC J-STD-020 JESD22-A113	MSL3 (85°C/85% RH, 168hrs) (3 Lots) – 77 units/Lot	(Results Are Pending)
Temperature Cycle	JESD22 A104	-65°C to +150°C for 500 cycles (3 Lots) – 77 units/Lot	(Results Are Pending)
uHAST (Unbiased HAST)	JESD22 A118	+130°C/85% RH, 96 hrs (3 Lots) – 77 units/Lot	(Results Are Pending)
CSAM	J-STD-035	(3 Lots) – 22 units/Lot	(Results Are Pending)
Notes: - Successful Qualification Criterion: “pass” on zero fails for each test depicted above. Reliability Qualification Results: (Results Are Pending)			